

Chemical mechanical polishing system and apparatus

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Inventor: CHEN HAI-CHING (TW)
Applicant: UNITED MICROELECTRONICS CORP (TW)
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Abstract of **TW480616B**

This invention provides a wafer carrier apparatus in chemical mechanical polishing equipment, which at least consists of a wafer carrier module used to hold a wafer face down; a retaining ring and a conditioning module connected with the wafer carrier module to protect the wafer edge from contacting with a polishing pad and thus deforming through polishing and to perform a conditioning step for the polishing pad; and a first supply module connected with the retaining ring and the conditioning module to rotate and push down the retaining ring and the conditioning module and to supply chemicals for the retaining ring and the conditioning module.

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